



## Product Change Notification / CENO-16DNCZ633

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### Date:

19-Oct-2022

### Product Category:

8-bit Microcontrollers

### PCN Type:

Manufacturing Change

### Notification Subject:

CCB 5332 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire material and 104x150 mils lead-frame paddle size for selected PIC16F153xx, PIC16F183xx, PIC16F184xx, PIC16LF15xx and PIC16LF18xx device families available in 14L SOIC (.150in) package.

### Affected CPNs:

[CENO-16DNCZ633\\_Affected\\_CPN\\_10192022.pdf](#)

[CENO-16DNCZ633\\_Affected\\_CPN\\_10192022.csv](#)

### Notification Text:

**PCN Status:**Initial Notification

**PCN Type:**Manufacturing Change

**Microchip Parts Affected:**Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:**Qualification of palladium coated copper with gold flash (CuPdAu) bond wire material and 104x150 mils lead-frame paddle size for selected PIC16F153xx, PIC16F183xx, PIC16F184xx, PIC16LF15xx and PIC16LF18xx device families available in 14L SOIC (.150in) package.

### Pre and Post Change Summary:



Availability											
Final PCN Issue Date											X

**Method to Identify Change:**Traceability code

**Qualification Plan:**Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Plan.

**Revision History:**October 19, 2022: Issued initial notification.

The change described in this PCN does not alter Microchip’s current regulatory compliance regarding the material content of the applicable products.

**Attachments:**

- [PCN\\_CENO-16DNCZ633\\_Pre and Post Change\\_Summary.pdf](#)
- [PCN\\_CENO-16DNCZ633\\_Qualification Plan.pdf](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

**Terms and Conditions:**

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN)

PIC16F18324-E/SL024  
PIC16F18324-E/SL  
PIC16LF18324-E/SL  
PIC16F18324-E/SLVAO  
PIC16F18324-I/SL  
PIC16LF18324-I/SL  
PIC16F18324-I/SLVAO  
PIC16LF18324T-I/SL020  
PIC16F18324T-I/SL027  
PIC16F18324T-I/SL028  
PIC16F18324T-I/SL  
PIC16LF18324T-I/SL  
PIC16F18324T-I/SLVAO  
PIC16F18324T-E/SL024  
PIC16F18324T-E/SL  
PIC16F18324T-E/SLVAO  
PIC16F18325-E/SL  
PIC16LF18325-E/SL  
PIC16F18325-E/SLVAO  
PIC16F18325-I/SL  
PIC16LF18325-I/SL  
PIC16F18325T-I/SL  
PIC16LF18325T-I/SL  
PIC16F18325T-E/SLVAO  
PIC16LF18323-E/SL  
PIC16F18323-E/SL  
PIC16F18323-E/SLVAO  
PIC16LF18323-E/SLVAO  
PIC16LF18323-I/SL  
PIC16F18323-I/SL  
PIC16F18323-I/SLVAO  
PIC16LF18323T-I/SLC01  
PIC16LF18323T-I/SL  
PIC16F18323T-I/SL  
PIC16F18323T-I/SLVAO  
PIC16LF18323T-E/SL  
PIC16F18323T-E/SL  
PIC16F18323T-E/SLVAO  
PIC16LF18323T-E/SLVAO  
PIC16F18424-E/SL  
PIC16F18425-E/SL  
PIC16LF18424-E/SL  
PIC16LF18425-E/SL  
PIC16F18424-I/SL  
PIC16F18425-I/SL  
PIC16LF18424-I/SL

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PIC16LF18425-I/SL

PIC16F18425-I/SLVAO

PIC16F18424T-I/SL

PIC16F18425T-I/SL

PIC16LF18424T-I/SL

PIC16LF18425T-I/SL

PIC16F18424T-E/SL

PIC16F18446-XPRESS

PIC16F18426-E/SL

PIC16LF18426-E/SL

PIC16F18426-I/SL

PIC16LF18426-I/SL

PIC16F18426T-I/SL

PIC16LF18426T-I/SL

PIC16F18326-E/SL

PIC16LF18326-E/SL

PIC16F18326-E/SLVAO

PIC16F18326-I/SL

PIC16LF18326-I/SL

PIC16F18326T-I/SL

PIC16LF18326T-I/SL

PIC16F18326T-E/SLVAO

PIC16F15325-E/SL

PIC16LF15325-E/SL

PIC16F15325-E/SLVAO

PIC16F15325-I/SL

PIC16LF15325-I/SL

PIC16F15325-I/SLVAO

PIC16F15325T-I/SL

PIC16LF15325T-I/SL

PIC16F15325T-E/SLVAO

PIC16F15324-E/SL

PIC16LF15324-E/SL

PIC16F15324-E/SLVAO

PIC16F15324-I/SLC02

PIC16F15324-I/SL

PIC16LF15324-I/SL

PIC16F15324-I/SLVAO

PIC16LF15324-I/SLVAO

PIC16F15324T-I/SLC02

PIC16F15324T-I/SL

PIC16LF15324T-I/SL

PIC16F15324T-E/SL

PIC16F15324T-E/SLVAO

PIC16F15323-E/SL

PIC16LF15323-E/SL

PIC16F15323-E/SLVAO

PIC16F15323-I/SL

PIC16LF15323-I/SL

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PIC16F153231-I/SL

PIC16LF15323T-I/SL